



## REMARKS

The present application is a continuation of U.S. Patent Application No. 09/840,748 filed April 23, 2001 (the "Parent Application"). The specification has been amended to add a paragraph reflecting this status. Also, a paragraph has been added to page 3. This addition is the same as that accepted in the Parent Application, being a restatement of the subject matter of originally filed claims 1 and 2. The new paragraph is directed to providing further specification support for a buffer layer.

Furthermore, claims 1-16 have been cancelled without prejudice to consideration in a continuing application and claims 20-36 have been added. Claims 17, 18 and 20-22 were allowed in the Parent Application, and have been presented again for consideration along with further inventive aspects of the subject application as defined by new claims 23-36. All claims are believed to be patentable over the references of record. An information disclosure statement accompanies this submission. Reconsideration of the present application as amended is respectfully requested.

Respectfully submitted,

L. Scott Paynter, Reg. No. 39,797  
Woodard, Emhardt, Moriarty  
McNett & Henry  
Bank One Center Tower  
11 Monument Circle, Suite 3700  
Indianapolis, Indiana 46204-5137  
(317) 634-3456